

B220/A - B260/A

2.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

Features

- Guard Ring Die Construction for Transient Protection
- Ideally Suited for Automated Assembly
- · Low Power Loss, High Efficiency
- Surge Overload Rating to 50A Peak
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application
- High Temperature Soldering: 260°C/10 Second at Terminal
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Notes 3 & 4)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SMA/SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: Cathode Band or Cathode Notch
- Weight: SMA 0.064 grams (Approximate)
 SMB 0.093 grams (Approximate)

SMA/SMB





Top View

Bottom View

Ordering Information (Note 5)

Part Number	Qualification	Case	Packaging
B2xxA-13-F	Commercial	SMA	5000/Tape & Reel
B2xx-13-F	Commercial	SMB	3000/Tape & Reel
B250Q-13	Automotive	SMB	3000/Tape & Reel
B240AQ-13-F	Automotive	SMA	5000/Tape & Reel

^{*} x = Device type, e.g. B260A-13-F (SMA package); B240-13-F (SMB package).

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Product manufactured with Date Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.
- 5. For packaging details, go to our website at http://www.diodes.com.

Marking Information



B2X0A = Product type marking code, ex: B220A (SMA package)
B2X0 = Product type marking code, ex: B230 (SMB package)

| | = Manufacturers' code marking

YWW = Date code marking

Y = Last digit of year (ex: 2 for 2002)

WW = Week code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	B220/A	B230/A	B240/A	B250/A	B260/A	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	30	40	50	60	V
RMS Reverse Voltage	V _{R(RMS)}	14	21	28	35	42	V
Average Rectified Output Current @ T _L = +100°C	Ιο			2.0			Α
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load		50			А		

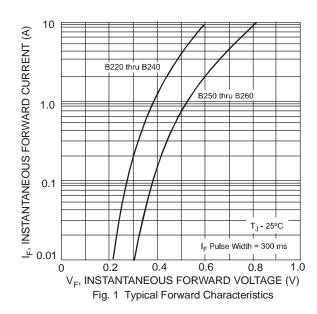
Thermal Characteristics

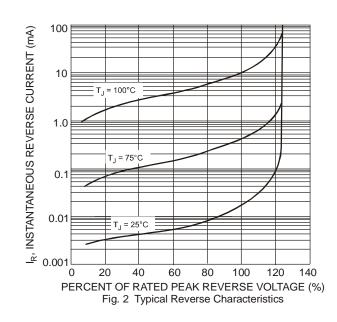
Characteristic		Symbol	Value	Unit	
Typical Thermal Resistance, Junction to Lead	SMA SMB	$R_{ heta}$ JL	25 20	°C/W	
Operating and Storage Temperature Range		T _J , T _{STG}	-65 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

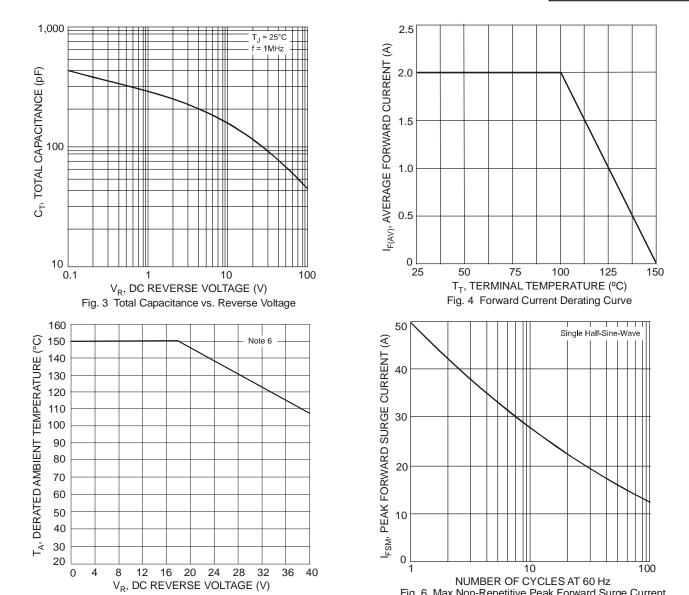
Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	B220/A, B230/A, B240/A B250/A, B260/A		-	ı	0.50 0.70	V	I _F = 2.0A, T _A = +25°C
Leakage Current (Note 6)		I _R	- -	1 1	0.5 20	mA	 @ Rated V_R, T_A = +25°C @ Rated V_R, T_A = +100°C
Total Capacitance		C _T	-	-	200	pF	$V_R = 4V$, $f = 1MHz$

Notes: 6. Short duration pulse test used to minimize self-heating effect.









6. Device mounted on FR-4 PC board with minimum recommended pad layout pattern as per http://www.diodes.com.

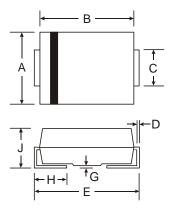
Fig. 5 Operating Temperature Derating (B240)

Fig. 6 Max Non-Repetitive Peak Forward Surge Current



Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

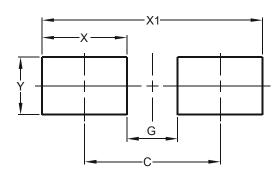


SMA			
Dim	Min	Max	
Α	2.29	2.92	
В	4.00	4.60	
С	1.27	1.63	
D	0.15	0.31	
Е	4.80	5.59	
G	0.05	0.20	
Н	0.76	1.52	
J	2.01	2.30	
All Dimensions in mm			

SMB				
Dim	Min	Max		
Α	3.30	3.94		
В	4.06	4.57		
С	1.96	2.21		
D	0.15	0.31		
Е	5.00	5.59		
G	0.05	0.20		
Н	0.76	1.52		
7	2.00	2.50		
All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



SMA			
Dimensions Value (in m			
С	4.00		
G	1.50		
Х	2.50		
X1	6.50		
Y	1.70		

SMB			
Dimensions	Value (in mm)		
С	4.30		
G	1.80		
Х	2.50		
X1	6.80		
Y	2.30		



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